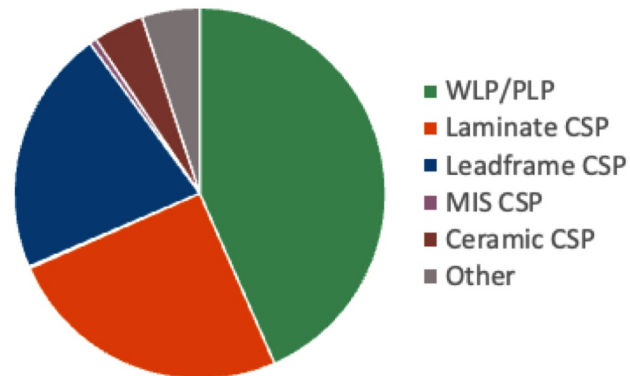


Samsung Galaxy Z Flip7

Teardown from TechSearch International, Inc.



159 Packages Examined



Contents and Highlights

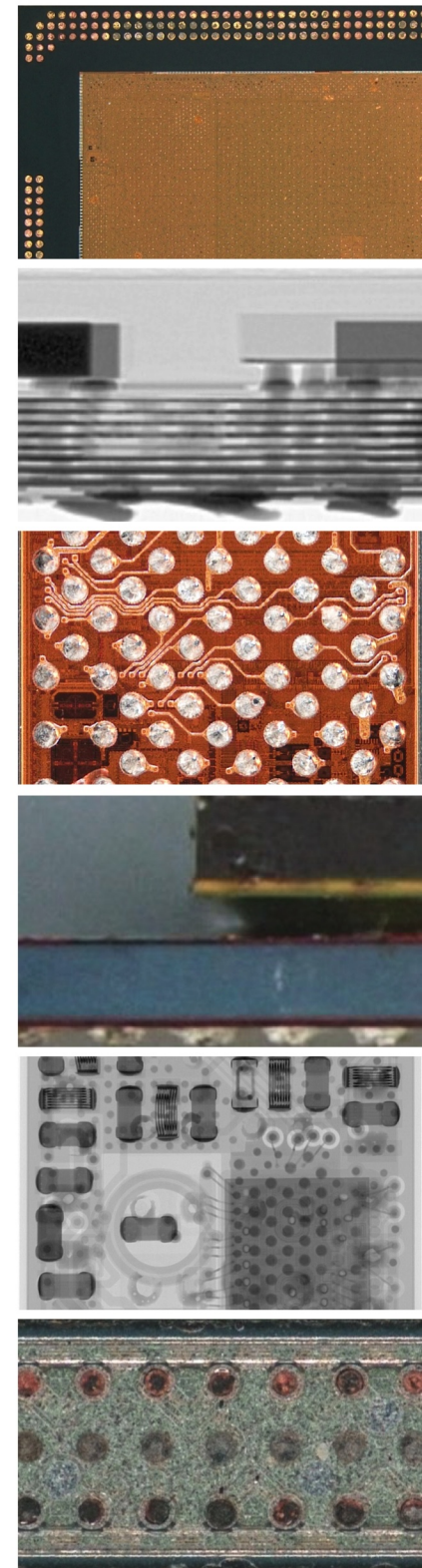
- 224-page report with package and die quantity summaries, high-resolution photos and X-rays, package dimensions, part numbers and descriptions, as well as analysis of packaging and assembly technologies discovered from package decapsulation
- 22 additional slides with construction analysis details for packages such as:
 - Exynos 2500 AP assembled by Samsung with fan-out WLP technology, featuring Murata flip chip decoupling capacitor IPDs on the underside
 - Micron 96Gb LPDDR5X with eight 12Gb die in four stacks
 - Qualcomm QPM7815A MB/HB FEM with DC
 - Skyworks SKY58098-11 MB/HM FEM
 - Murata SS5 5G mmWave module with Samsung transceiver and PMIC die inside
 - Samsung S3SSE2A post-quantum cryptography (PQC) security chip

Teardowns backed by 39 years serving as the industry's trusted source for semiconductor packaging trend analysis

- Examination of all chips with emphasis on assembly and packaging technologies
- Superb quality photographs and x-ray images
- Both the packages and the die within are identified and characterized
- Detailed construction analysis of key chips and packages



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